



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re Application of:

Ball et al.

Serial No.: 09/854,759

Filed: May 14, 2001

**For: USING BACKGRIND WAFER TAPE
TO ENABLE WAFER MOUNTING OF
BUMPED WAFERS**

Confirmation No.: 8899

Examiner: J. Haran

Group Art Unit: 1733

Attorney Docket No.: 4589US (99-1151)

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CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

February 14, 2003
Date

Signature

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AMENDMENT

Box NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Sir:

This Amendment is in response to the Office Action mailed on November 20, 2002, whose initial period of response is set to expire on February 20, 2002.